



Description

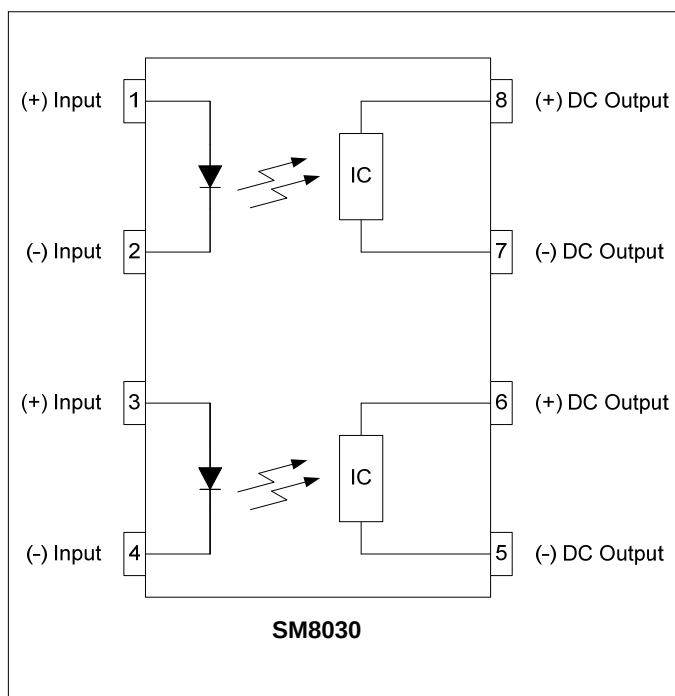
The SM8030 is composed of two distinct MOSFET drivers in a single package. Each driver circuit consists of an input drive LED optically coupled to a photodiode array output designed to drive highly capacitive loads, including the gate of a power MOSFET. The active discharge circuit of the PDAs assures quick discharge of MOSFETs, providing fast turn-off times. This device can be used as two separate drivers, or can be wired as a single enhanced driver with either greater photo current or photo voltage output.

The SM8030 comes standard in a compact 8 pin DIP package making it ideal for high-density board applications.

Applications

- Isolated means to drive discrete power MOSFETs
- Lighting Controls
- Process Control Modules
- Solid State Relays
- Solenoid Controls

Schematic Diagram



Features

- Compact 8 pin DIP/SMD package
- Built in active discharge circuit for fast turn-off
- Fast Turn-On
- Optional Parallel or Serial Output Connections
- 12V Gate Drive Voltage
- High Input-to-Output Isolation (up to 5kV_{RMS})
- Long Life / High Reliability
- RoHS / Pb-Free / REACH Compliant

Agency Approvals

UL/C-UL: File # E201932
 VDE: File # 40035191 (EN 60747-5-2)

Absolute Maximum Ratings

The values indicated are absolute stress ratings. Functional operation of the device is not implied at these or any conditions in excess of those defined in electrical characteristics section of this document. Exposure to absolute Maximum Ratings may cause permanent damage to the device and may adversely affect reliability.

Storage Temperature-55 to +125°C
 Operating Temperature-40 to +85°C
 Continuous Input Current50mA
 Transient Input Current400mA
 Reverse Input Control Voltage5V
 Input Power Dissipation40mW
 Output Power Dissipation400mW
 Solder Temperature – Wave (10sec).....260°C
 Solder Temperature – IR Reflow (10sec).....260°C

Ordering Information

Part Number	Description
SM8030	8 pin DIP, (50/Tube)
SM8030-H	5kV _{RMS} Viso, 8 pin DIP, (50/Tube)
SM8030-S	8 pin SMD, (50/Tube)
SM8030-HS	5kV _{RMS} , 8 pin SMD, (50/Tube)
SM8030-STR	8 pin SMD, Tape and Reel (1000/Reel)
SM8030-HSTR	5kV _{RMS} , 8 pin SMD, Tape and Reel (1000/Reel)

NOTE: Suffixes listed above are not included in marking on device for part number identification

Electrical Characteristics, $T_A = 25^\circ\text{C}$ (unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Input Specifications						
LED Forward Voltage	V_F	-	2.8	3.5	V	$I_F = 10\text{mA}$
LED Reverse Voltage	BV_R	5	-	-	V	$I_R = 10\mu\text{A}$
Reverse Leakage Current	I_{InRleak}	-	-	10	μA	$V_R = 5\text{V}$
Turn-On Current	I_F	-	5	10	mA	$V_{\text{OUT}} = 5\text{V}$
Turn-Off Current	$I_{F(\text{OFF})}$	-	0.5	-	mA	$V_{\text{OUT}} = 2\text{V}$
Output Specifications						
Open Circuit Voltage	V_{OC}	12	14	-	V	$I_F = 10\text{mA}$
Short Circuit Voltage	I_{SC}	20	25	-	μA	$I_F = 10\text{mA}$
Isolation Specifications						
Isolation Voltage (-H Option)	V_{ISO}	3750	-	-	V_{RMS}	$\text{RH} \leq 50\%, t=1\text{min}$
		5000	-	-		
Input-Output Resistance	$R_{\text{I-O}}$	-	10^{12}	-	Ω	$V_{\text{I-O}} = 500V_{\text{DC}}$

SM8030 Solder Temperature Profile Recommendations

(1) Infrared Reflow:

Refer to the following figure as an example of an optimal temperature profile for single occurrence infrared reflow. Soldering process should not exceed temperature or time limits expressed herein. Surface temperature of device package should not exceed 250°C:

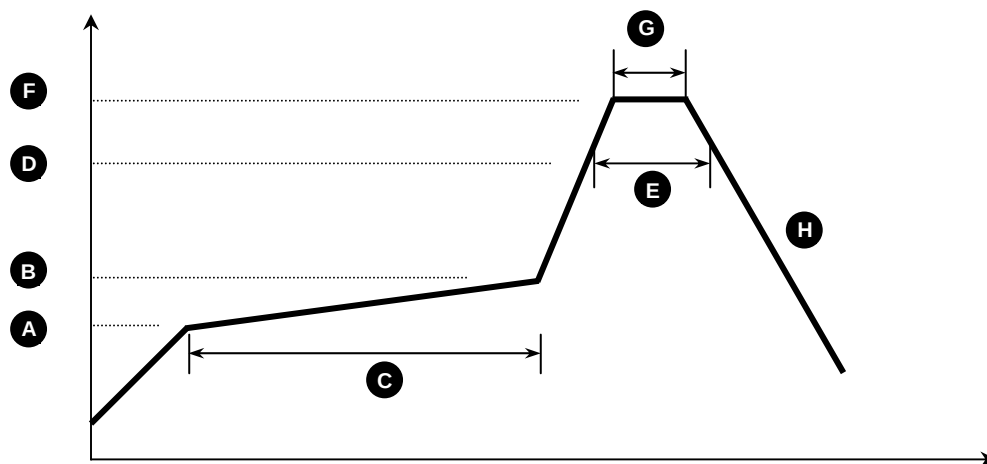


Figure 1

Process Step	Description	Parameter
A	Preheat Start Temperature (°C)	150°C
B	Preheat Finish Temperature (°C)	180°C
C	Preheat Time (s)	90 - 120s
D	Melting Temperature (°C)	230°C
E	Time above Melting Temperature (s)	30s
F	Peak Temperature, at Terminal (°C)	260°C
G	Dwell Time at Peak Temperature (s)	10s
H	Cool-down (°C/s)	<6°C/s

(2) Wave Solder:

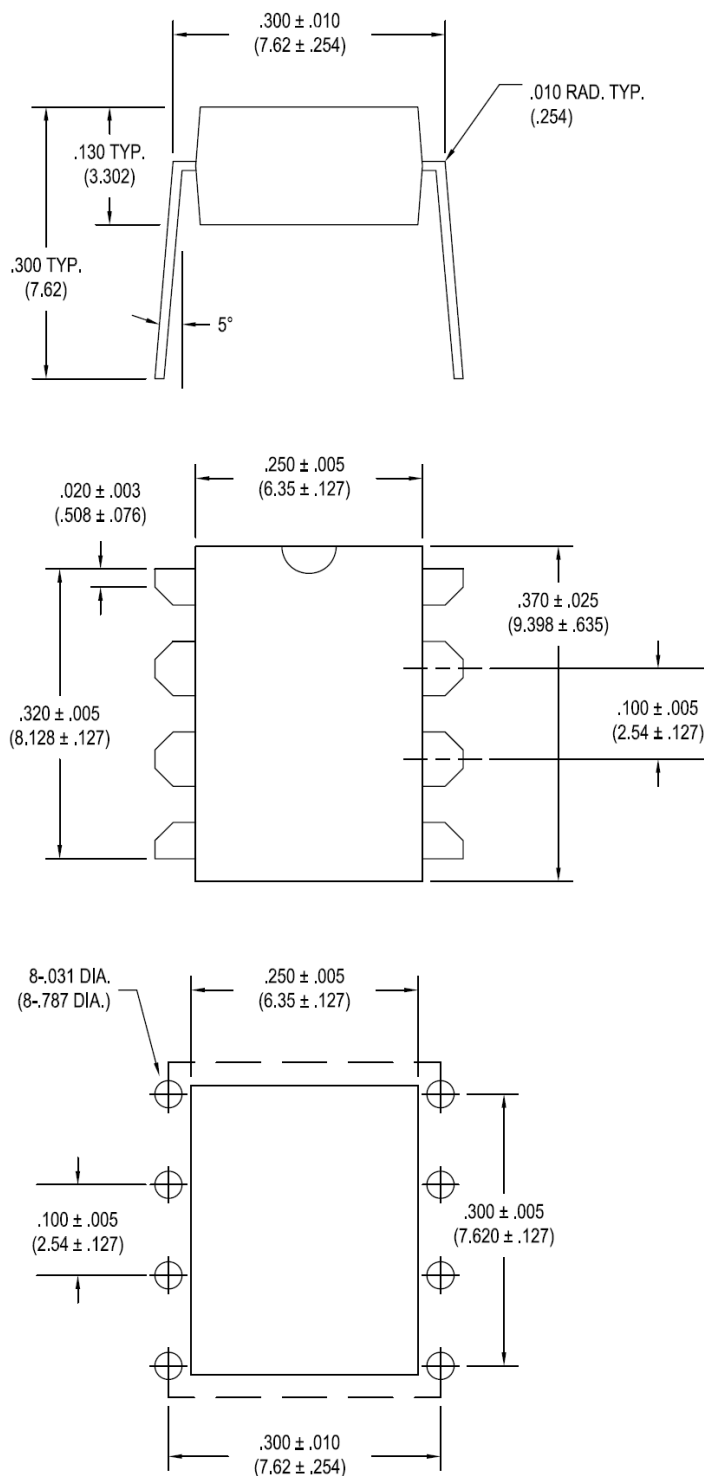
Maximum Temperature: 260°C (at terminal)
 Maximum Time: 10s
 Pre-heating: 100 - 150°C (30 - 90s)
 Single Occurrence

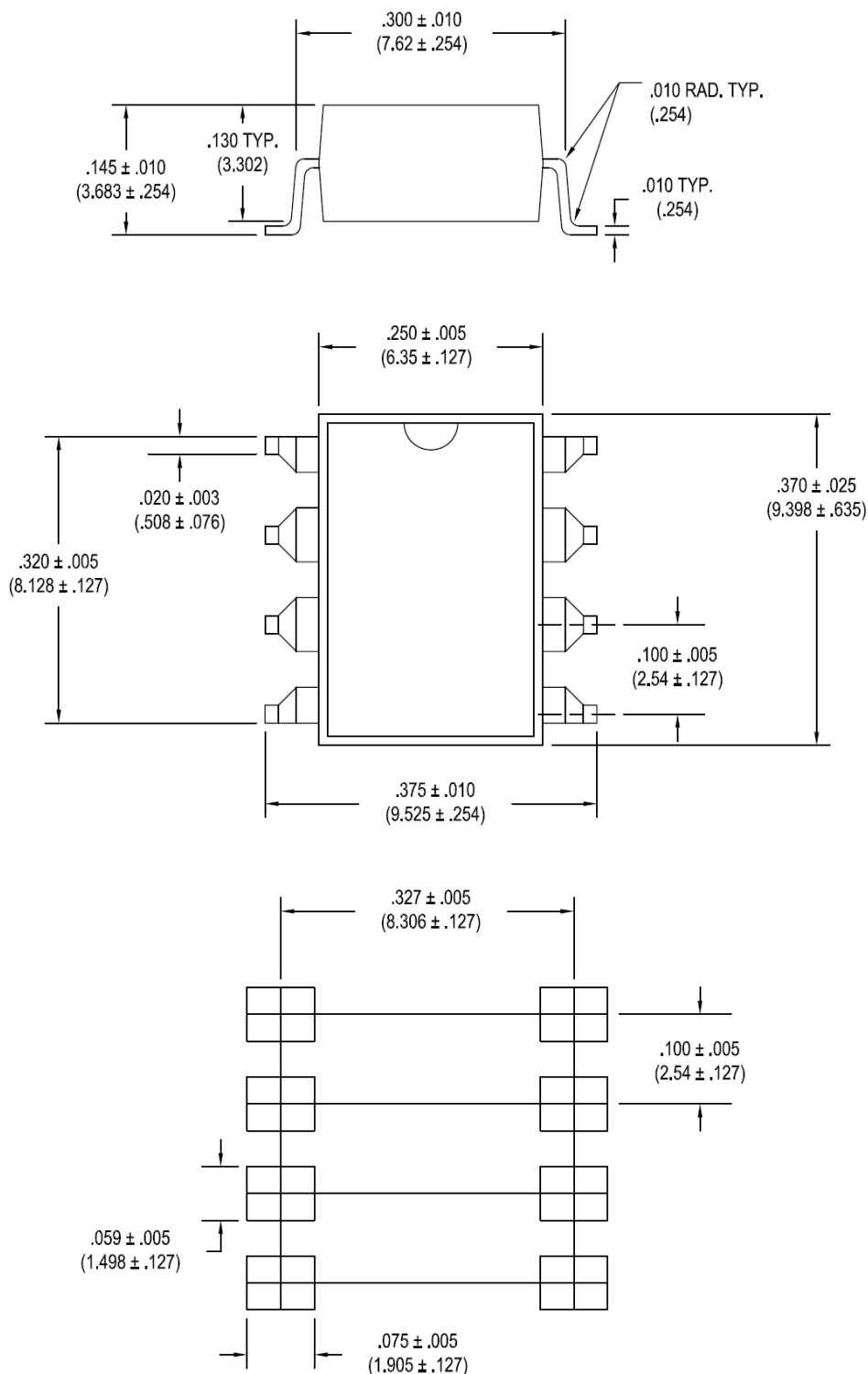
(3) Hand Solder:

Maximum Temperature: 350°C (at tip of soldering iron)
 Maximum Time: 3s
 Single Occurrence

SM8030 Package Dimensions
8 PIN DIP Package

Note: All dimensions in inches ["] with millimeters in parenthesis ()

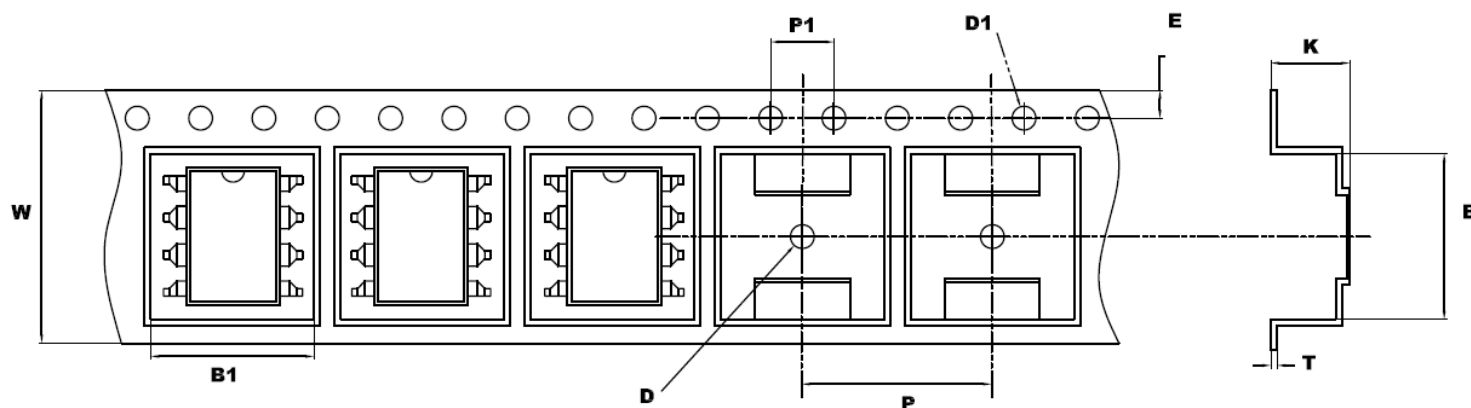


SM8030 Package Dimensions
8 PIN SMD Surface Mount Package (-S)
Note: All dimensions in inches ["] with millimeters in parenthesis ()


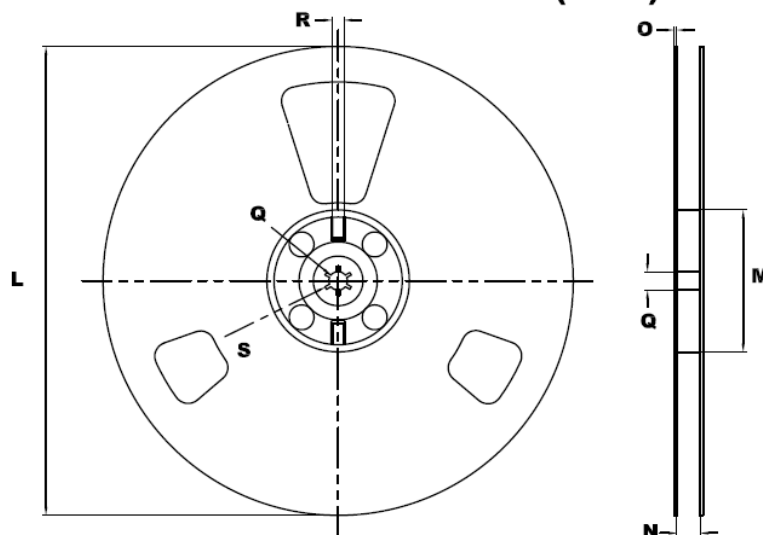
SM8030 Package Dimensions

8 PIN SMD Tape & Reel (-STR)

Note: All dimensions in millimeters

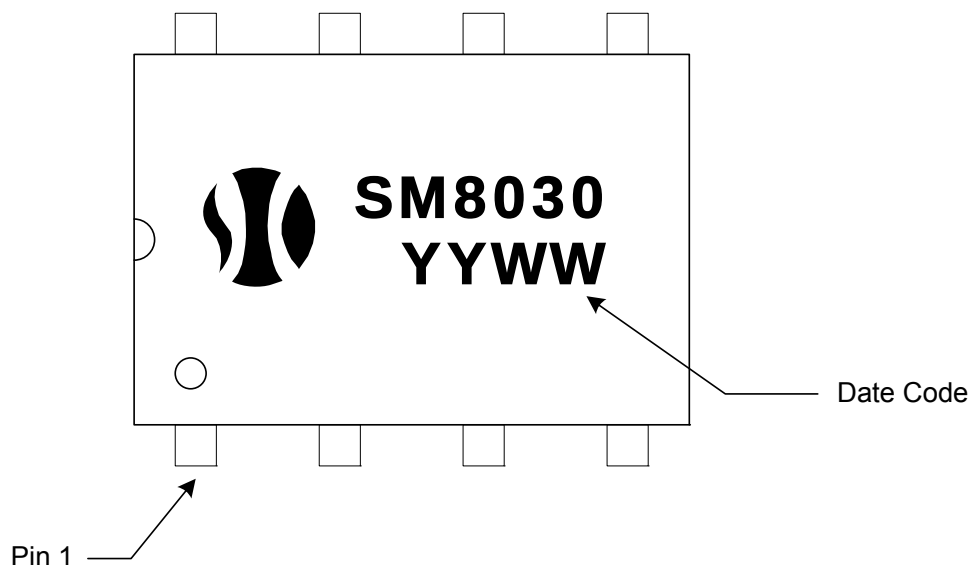
Outline and Dimension (Tape)


W	B	B1	P	P1	K	E	T	D	D1
16.00 ±0.1	10.50 ±0.1	10.30 ±0.1	12.00 ±0.1	4.00 ±0.1	5.00 ±0.1	1.75 ±0.1	0.40 ±0.1	1.50 ±0.1	1.50 ±0.1

Outline and Dimensions (Reel)

Packaging: 1,000 pcs / reel

L	M	N	O	Q	R	S
330.00	100.00	16.40 ±0.2	2.00 ±0.1	13.00 ±0.2	2.00	10.00

SM8030 Package Marking



SM8030 Package Weights

Device	Single Unit	Full Tube (50pcs)	Full Pouch (10 tubes)	Full Reel (1000pcs)
SM8030(-H)	0.54	43	450	-
SM8030(-H)S	0.53	42	440	-
SM8030(-H)STR	0.53	-	-	952

Note: All weights above are in GRAMS, and include packaging materials where applicable

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